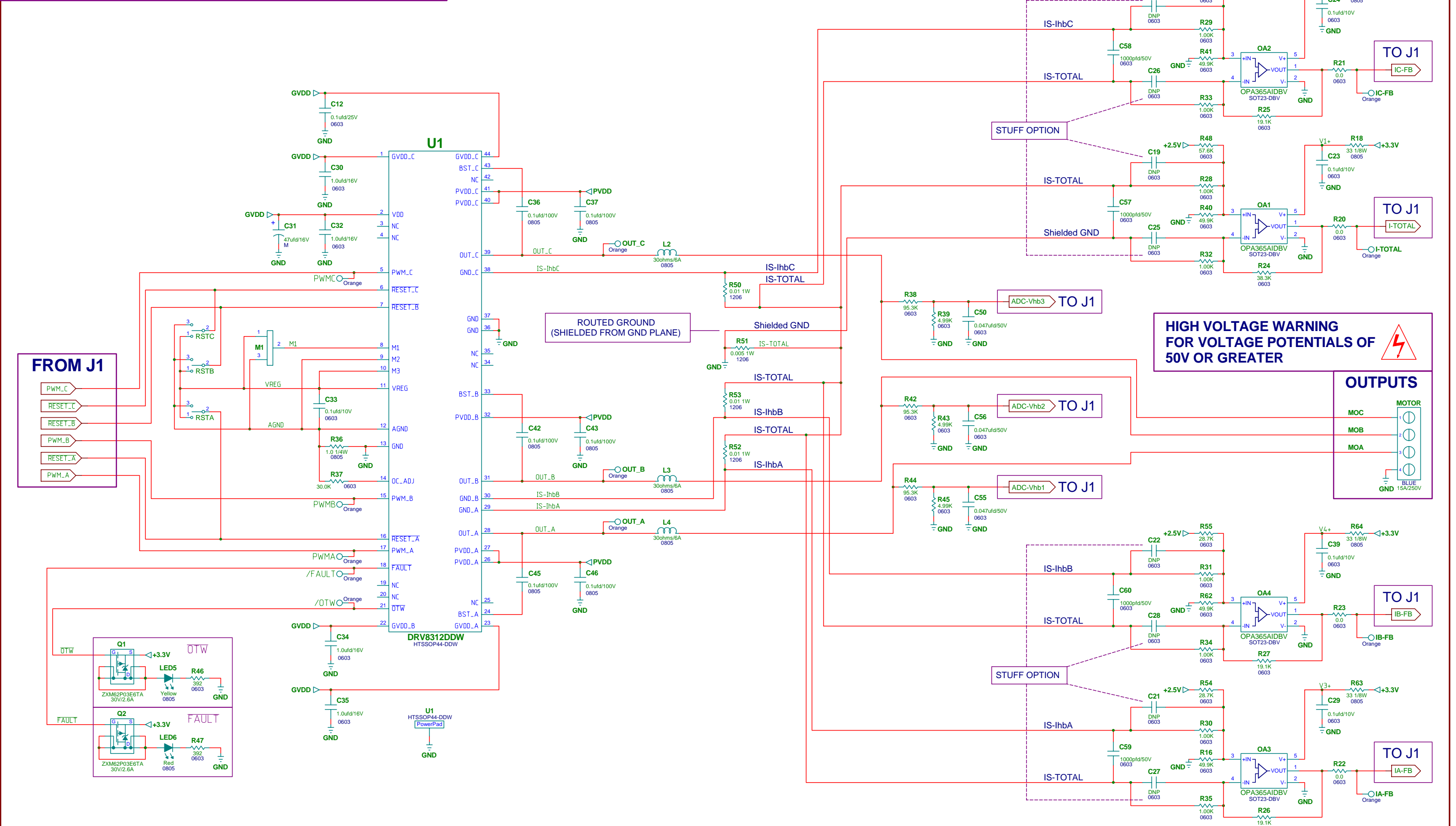
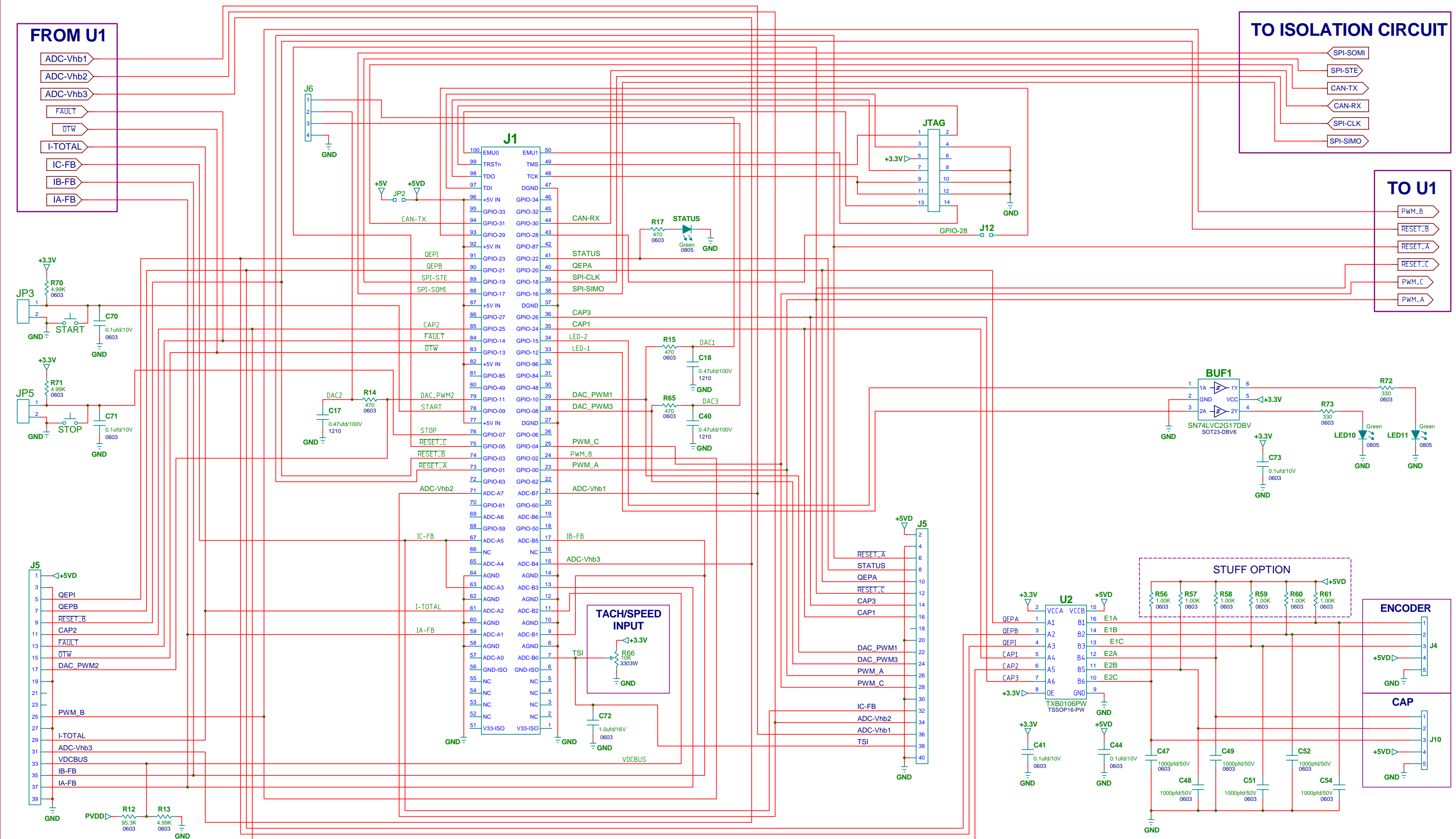


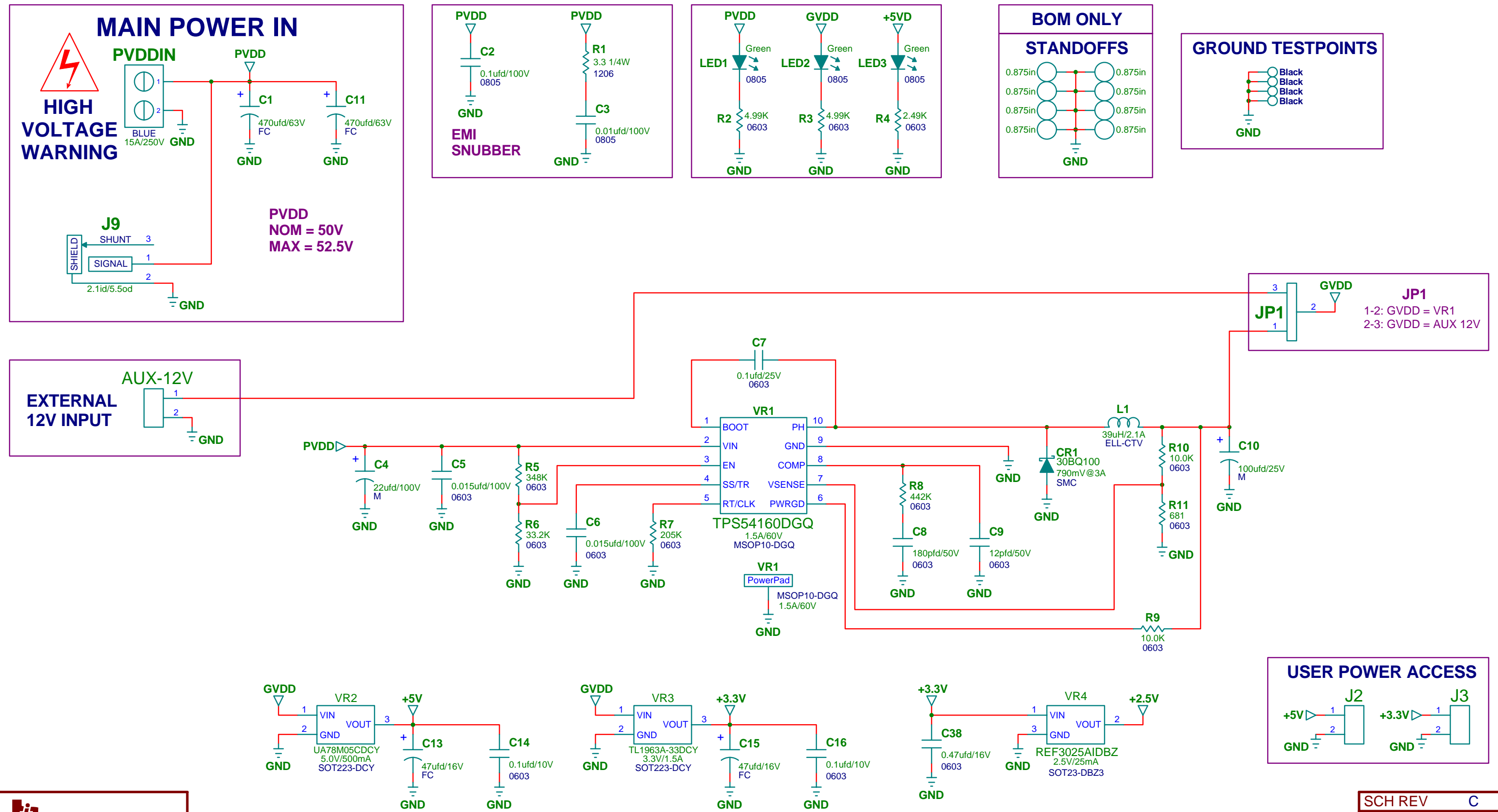
DRV8312 EVALUATION BOARD



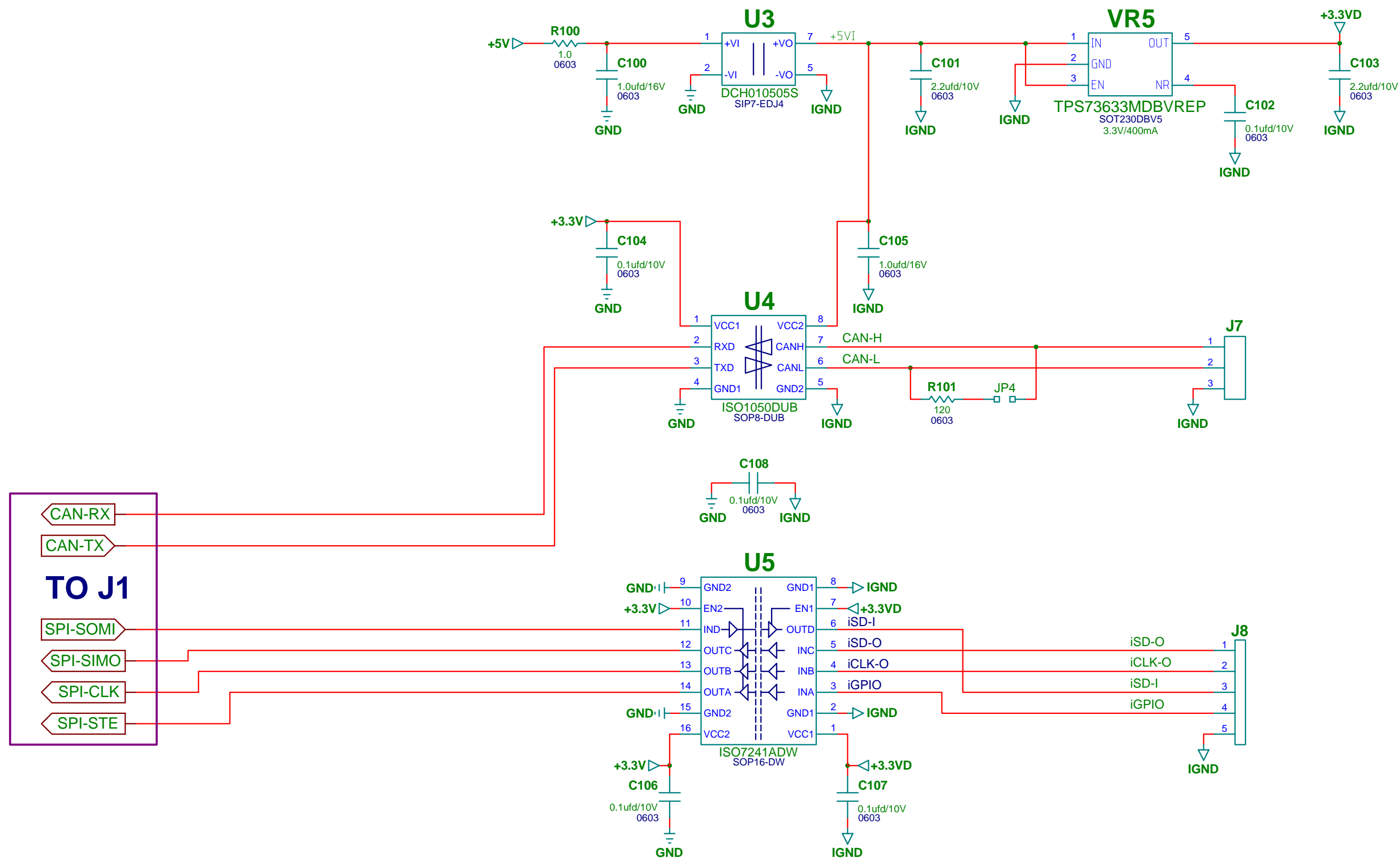
DRV8312 EVALUATION BOARD



DRV8312 EVALUATION BOARD



DRV8312 EVALUATION BOARD



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DRV8312 EVALUATION BOARD

REVISION HISTORY			
REVISION	DESCRIPTION	DATE	APPROVAL
A	INITIAL RELEASE	MAY 4, 2010	ML
B	1. DELETED OUTA, OUTB, OUTC. 2. ADDED OUTPUT CONNECTOR, TITLED MOTOR. 3. CONNECTED L2-2, L3-2 AND L4-2 TO MOTOR-1,2 AND 3, RESPECTIVELY. 4. DELETED PVDD, GND, +12V AND GND(GND2). 5. ADDED POWER CONNECTOR, VIN. 6. CONNECTED VIN-4 TO C1-1. 7. CONNECTED VIN-2,3 TO GND. 8. CONNECTED VIN-1 TO +12V. 9. ADDED TESTPOINTS TO IA-FB, IB-FB, IC-FB AND I-TOTAL. 10. ADDED 2 PIN HEADERS J2 AND J3 FOR USER POWER ACCESS. 11. CONNECTED J2-1,2 TO +5V AND GND. 12. CONNECTED J3-1,2 TO +3.3V AND GND. 13. COMBINED ENCODER AND CAP INTO ONE 2x5 HEADER, TITLED J4. 14. ADDED 3 PIN HEADER, JP3, LABELED TACH/SPEED INPUT. 15. CONNECTED JP3-1,2,3 TO +3.3V, J1-7 AND GND, RESPECTIVELY. 16. RENAMED S1 TO RSTA. 17. SWAPPED U1-29 AND U1-30. 18. ADDED 40 PIN HEADER, J5 AND CONNECTED PINS TO ACTIVE PINS OF J1. 19. ADDED SWITCHES, S1 AND S2 TO U1-76 AND U1-78. 20. COPIED DAC1 CIRCUIT, CALLED DAC3, AND CONNECTED TO J1-28. 21. CHANGED R24-R27 TO 33.0K OHMS. 22. CHANGED R28-R35, R56-R61 TO 1.00K OHMS. 23. CHANGED R48, R49, R54 AND R55 TO 49.9K OHMS. 24. ADDED ISOLATION CIRCUITS. 25. ADDED 12V CONNECTOR, J9. 26. CHANGED C4 TO 22UFD/100V. 27. CHANGED C5 AND C6 TO 100V.	MARCH 23, 2011	RK

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